

IN THE CLAIMS:

No claims have been amended herein. Claims 14 through 21 are newly added with this amendment. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Original) A lead frame for an integrated circuit package comprising:
a composite lead frame of a plastic material having a portion thereof including an intrinsic
conductive polymer.
2. (Previously Presented) The lead frame of claim 1, further comprising:
an adhesive located on a portion of the composite lead frame.
3. (Previously Presented) The lead frame of claim 1, wherein the intrinsic
conductive polymer is a polyaniline.
4. (Previously Presented) The lead frame of claim 1, wherein the composite lead
frame is transparent.
5. (Previously Presented) A circuit card comprising:
at least one electronic device;
a circuit card; and
at least one connector for attaching a portion of the at least one electronic device to a portion of
the circuit card, the at least one electronic device comprising an integrated circuit die
attached to a portion of a plastic lead frame, the plastic lead frame including an intrinsic
conductive polymer.

6. (Previously Presented) The circuit card of claim 5, wherein the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymer.
7. (Previously Presented) The circuit card of claim 6, wherein the conductive polymer coating is selected from the group consisting of polyaniline.
8. (Previously Presented) The circuit card of claim 7, wherein the polyaniline coating is of a thickness between about 25 μm and about 75 μm .
9. (Previously Presented) The circuit card of claim 5, wherein the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.
10. (Previously Presented) A computer system comprising at least one circuit card, the at least one circuit card comprised of a plurality of electronic devices, at least one electronic device of the plurality comprising at least one integrated circuit die connected to a portion of a plastic lead frame including an intrinsic polymer material.
11. (Previously Presented) The computer system of claim 10, wherein the plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymeric coating.
12. (Previously Presented) The computer system of claim 11, wherein the conductive polymeric coating is selected from the group consisting of polyaniline.
13. (Previously Presented) The computer system of claim 10, wherein the plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.

Please add the following new claims:

14. (New) An encapsulated semiconductor assembly including portions of a lead frame extending therefrom and an integrated circuit die comprising:
a lead frame of a plastic material that is conductive;
an integrated circuit die having a plurality of bond pads on a surface thereof; and
at least one connection between a portion of the lead frame and at least one bond pad of the integrated circuit die..
15. (New) The assembly of claim 14, further comprising:
an adhesive located on a portion of the lead frame.
16. (New) The assembly of claim 1, wherein the intrinsic conductive polymer comprises a polyaniline.
17. (New) The assembly of claim 14, wherein the lead frame comprises a transparent lead frame.
18. (New) The assembly of claim 14, wherein the at least one connection comprises a bond wire.
19. (New) The assembly of claim 14, wherein the at least one connection comprises a conductive epoxy.
20. (New) The assembly of claim 14, wherein the at least one connection comprises a Z-axis conductive material.
21. (New) The assembly of claim 14, wherein the at least one connection comprises a direct connection.